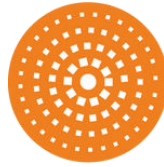


VAC Range

Vapour Phase Reflow Furnaces with or without vacuum for superior soldering quality



PYROX

DIVISION ELECTRONIQUE

IBL

+ TECHNICAL

Optimal soldering quality.

+ FINANCIAL

The most cost-effective solution on the market.

+ ECO-FRIENDLY

Environmentally friendly.



The new VAC range, available in batch and in-line versions, guarantees superior soldering quality without voids (in solder joints). Vapour phase technology combined with vacuum processing significantly increases the reliability of the finished product. Soldering is carried out in a completely inert atmosphere without nitrogen (for improved solder paste wetting) throughout the reflow process, with or without vacuum. These furnaces offer great flexibility thanks to their many features. The dual-process chamber design, the complete absence of assembly overheating, and the very low energy consumption help to significantly reduce operating costs compared to conventional reflow systems.



General

- 2 different models according to board size/production
- Compact footprint
- Dual-process chamber design
- Soldering without oxygen or added nitrogen
- No overheating of components
- Low energy consumption



Features

- Very low void rate (< 2%)
- Unlimited programme memory capacity
- Simple and user-friendly 15" touchscreen interface
- Continuous machine data logging
- Wide range of pre-set soldering profiles
- Low heat transfer fluid consumption thanks to dual-chamber design and fluid recovery system
- Integrated ventilated cooling system
- Minimal maintenance and wear (all moving parts outside vapour zone)
- 4 internal channels for optimised temperature measurement and profiling
- Energy management system
- Controlled fluid level + automatic filtration
- Automated infeed/outfeed loading



Technical Specifications

- Patented vapour phase reflow process under vacuum for void-free soldering (**patented**)
- Two available processes: reflow with or without vacuum
- IPS, Intelligent Profiling System, for:
 - Temperature-regulated profiles (SVTC: Soft Vapour Temperature Control)
 - Guided mode: setup and profiling in one step
- Leaded and lead-free soldering with a single fluid for different peak temperatures
- Integrated profiling software without external data logger
- Synchronous mode (hot basket / cold basket) for cycle repeatability
- Maintenance-free transport system (**patented**)
- Easy access to the vapour chamber for maintenance operations



Let's innovate together to reinvent
today's materials and discover
tomorrow's.

AET GROUP

73D rue Général Mangin
38100 Grenoble - FRANCE

sales@aet.group
+33 (0)4 76 90 41 18

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Options

- IPSC function (guided mode for control and recording of the assembly profile)
- Rapid Cooling System (RCS) (**patented**)
- IR heating element system (**patented**)
- Process data logging and analysis software (TRS system)
- Barcode for automatic programme change, traceability and unlimited storage
- Additional process temperature measurement channels
- Multi-level mode for easy adjustment of different PCB heights using tooling
- Adapter for top/bottom side PCB reflow
- Backup power module (UPS)
- In-line operation module
- Additional cooling unit (front chamber) based on process requirements
- Self-contained cooling unit



Technical Specifications*	VAC745	VAC765	VAC745i	VAC765i
Overall length	1355 mm		2040 mm	
Depth	2400 mm	2810mm	3040 mm	3450 mm
Height	1470 mm		1470 mm	
Weight	1030 kg	1200 kg	1290 kg	1450 kg
Max board size (in-line)	na	na	630 x 400 x 50 mm avec vide 630 x 400 x 60 mm sans vide	
Max board size (batch)	635 x 444 x70mm with vaccum 635 x 444 x 80mm without vaccum	635 x 644 x70mm with vaccum 635 x 644 x 80mm without vaccum	635 x 444 x 70 mm with vaccum 635 x 444 x 80 mm without vaccum	635 x 644 x 70 mm with vaccum 635 x 644 x 80 mm without vaccum
Heat transfer fluid capacity	40 kg	60 kg	40 kg	60 kg
Water connection	1/2" / 2,5 – 5 bar			
Max heating power	10,4kW	13 kW	10,4 kW	13 kW
Power consumption	5,5 kW/h	5,8 kW/h	5,5 kW/h	5,8 kW/h
Electrical supply	230 / 400 VAC, 50/60Hz			
Main fuse	32A „gI“ or „C“			
External vacuum module (L x W x H, weight)	910 x 550 x 650mm , 119 kg			

*subject to technical modifications



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